

ABSTRACT OF THE DISCLOSURE

An integrated circuit package separator method for separating integrated circuit packages from a board having a plurality of integrated circuits. The method includes providing a base having a plurality of pins, providing a support over the base and having a plurality of holes extending therethrough, the plurality of pins extending through the plurality of holes, vertically displacing the support off the pins using a pair of pneumatic actuators such that each of the pneumatic actuators lift respective opposing ends of the support substantially simultaneously and in unison, providing each of the pneumatic actuators with release valves to equilibrate a back-pressure to ambient during lifting of the support, and separating the integrated circuit packages from one another when the board is over the upper surface of the support.